



Product Change Notification - KSRA-19VAHD748 [\(Printer Friendly\)](#)

Date:

29 Jan 2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Notification subject:

CCB 2924 and 2924.001 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited (NSEB)		UTAC Thai Limited (NSEB)
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	C194		C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 01, 2018 (date code: 1809)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2017						-->	January 2018					->	March 2018				
	13	14	15	16	17	18		01	02	03	04	05		09	10	11	12	13
Initial PCN Issue Date				X														
Qual Report Availability										X								
Final PCN Issue Date										X								
Estimated												X						

